

Title (en)

CIRCUIT CARRIER, (POWER) ELECTRONICS ASSEMBLY AND ELECTRICAL DRIVE DEVICE

Title (de)

SCHALTUNGSTRÄGER, (LEISTUNGS-)ELEKTRONIKANORDNUNG UND ELEKTRISCHE ANTRIEBSVORRICHTUNG

Title (fr)

CARTE DE CIRCUIT IMPRIMÉ, DISPOSITIF ÉLECTRONIQUE (DE PUISSANCE) ET DISPOSITIF D'ENTRAÎNEMENT ÉLECTRONIQUE

Publication

EP 3881652 A1 20210922 (DE)

Application

EP 19813729 A 20191113

Priority

- DE 102018219574 A 20181115
- EP 2019081131 W 20191113

Abstract (en)

[origin: WO2020099464A1] The present invention discloses a circuit carrier (20) for establishing a mechanical and electrical connection for at least one (power) electronic component (500), comprising: - a support plate (100) which has at least one through-hole (200); - at least one electrically and thermally conductive insertion element (300) which is arranged in the through-hole (200) and has a first contact surface (301) for establishing electrical and thermal connections to the component (500) and a second contact surface (302), facing away from the first contact surface (301), for establishing thermal connections to a cooling body (600); - wherein the insertion element (300) also forms a feedthrough (210) and has a lateral contact face (303) which abuts the feedthrough (210) and is designed to establish an electrical and thermal connection to an electrical connection element (710).

IPC 8 full level

H05K 1/02 (2006.01); **H02K 11/33** (2016.01); **H02M 7/00** (2006.01); **H05K 1/18** (2006.01); **H05K 3/00** (2006.01)

CPC (source: EP US)

B60L 53/20 (2019.01 - US); **B60R 16/0231** (2013.01 - US); **H02K 9/223** (2021.01 - EP US); **H02K 9/227** (2021.01 - EP US); **H02K 11/33** (2016.01 - EP US); **H02M 7/003** (2013.01 - EP); **H05K 1/0265** (2013.01 - EP); **H05K 1/18** (2013.01 - EP); **H05K 1/181** (2013.01 - EP); **H05K 3/0061** (2013.01 - EP); **H02K 2211/03** (2013.01 - US); **H02M 1/327** (2021.05 - EP); **H05K 1/0204** (2013.01 - EP); **H05K 2201/066** (2013.01 - EP); **H05K 2201/1009** (2013.01 - EP); **H05K 2201/10166** (2013.01 - EP); **H05K 2201/10272** (2013.01 - EP); **H05K 2201/10303** (2013.01 - EP); **H05K 2201/10416** (2013.01 - EP); **Y02P 70/50** (2015.11 - EP); **Y02T 10/70** (2013.01 - EP); **Y02T 10/7072** (2013.01 - EP); **Y02T 90/14** (2013.01 - EP)

Citation (search report)

See references of WO 2020099464A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

DE 102018219574 A1 20200520; CN 113039870 A 20210625; EP 3881652 A1 20210922; US 2021273533 A1 20210902; WO 2020099464 A1 20200522

DOCDB simple family (application)

DE 102018219574 A 20181115; CN 201980075132 A 20191113; EP 19813729 A 20191113; EP 2019081131 W 20191113; US 202117320570 A 20210514